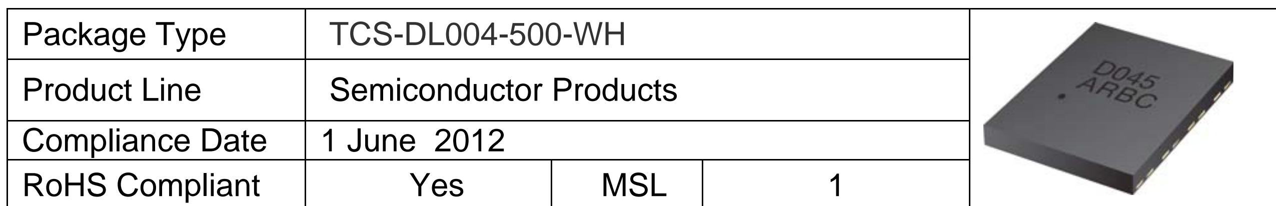
MATERIAL DECLARATION SHEET



Package Type	TCS-DL004-500-WH		
Product Line	Semiconductor Products		
Compliance Date	1 June 2012		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.018911	Fused Silica	60676-86-0	87.70	43.99	50.16
				Epoxy resin	Trade secret	5.00	2.51	
				Epoxy CN	29690-82-2	2.00	1.00	
				Phenol resin	Trade secret	5.00	2.51	
				Carbon Black	1333-86-4	0.30	0.15	
2	Leadframe	Copper alloy	0.014603	Copper	7440-50-8	93.32	36.24	38.73
				Iron	7439-89-6	2.20	0.85	
				Zinc	7440-66-6	0.01	0.00	
				Phosphorous	7723-14-0	0.03	0.01	
				Silver (Plating)	7440-22-4	4.45	1.63	
3	Chip	Silicon	0.003401	Silicon	7440-21-3	99.43	9.01	9.02
				Aluminum	7429-90-5	0.57	0.01	
4	Die Attach	Silver epoxy	0.000132	Silver	7440-22-4	75.00	0.26	0.35
				Epoxy	9003-36-5	25.00	0.09	
5	Bond wires	Gold	0.000051	Gold	7440-57-5	100.00	0.13	0.13
6	Terminal Finish	Matte Tin	0.000602	Matte Tin	7440-31-5	100.00	1.60	1.60
		Total Weight	0.0377000					

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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